



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

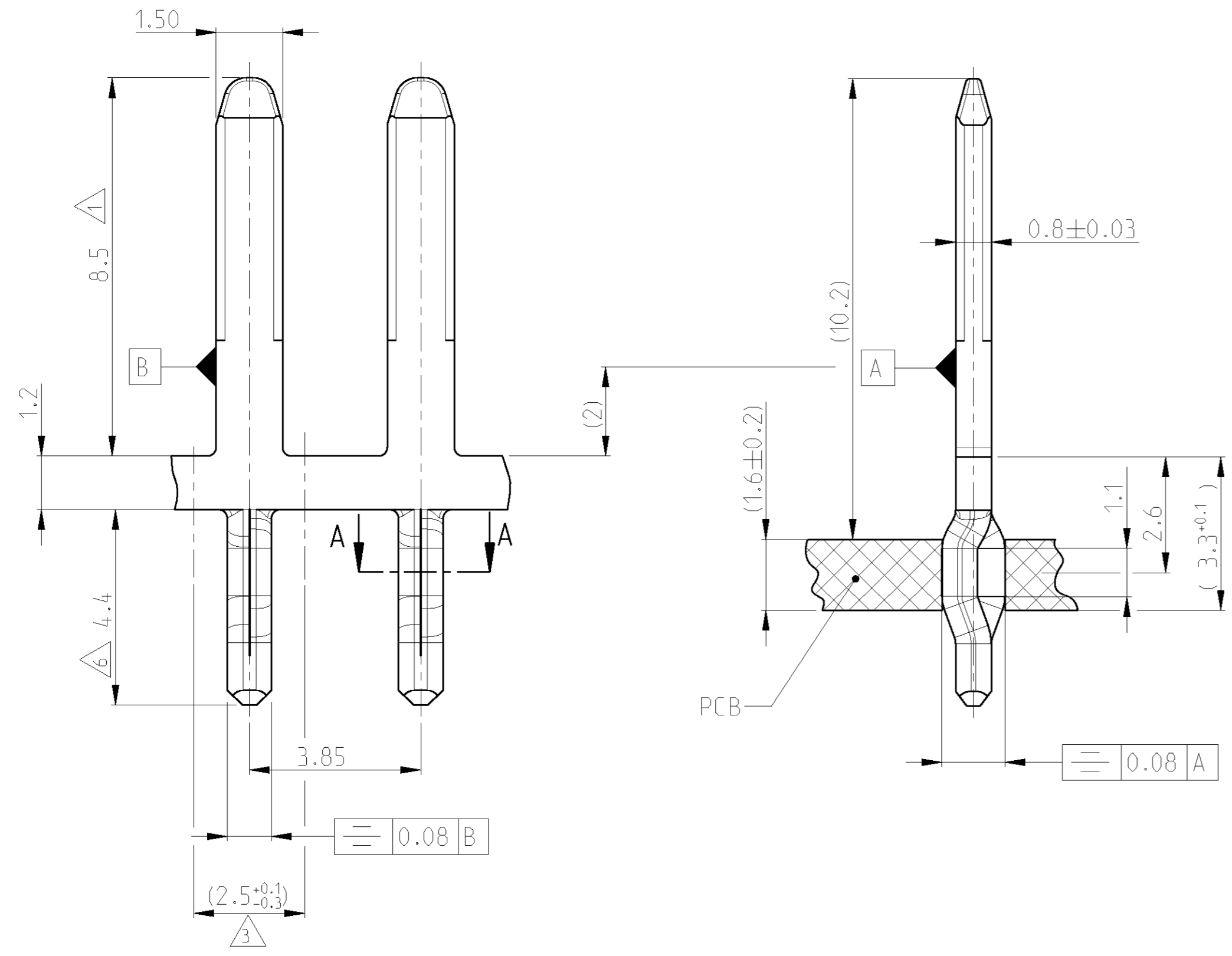
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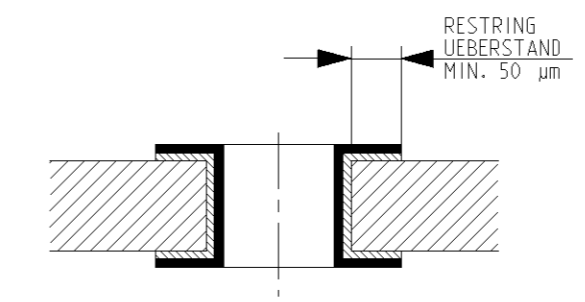
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



REVISIONS							
LOC	DIST	P	LTR	DESCRIPTION	DATE	DWN	APVD
A1	-			Note 5 von Kunststoffspule auf Hartfaserspule geändert	14NOV2005	PNI	JRY



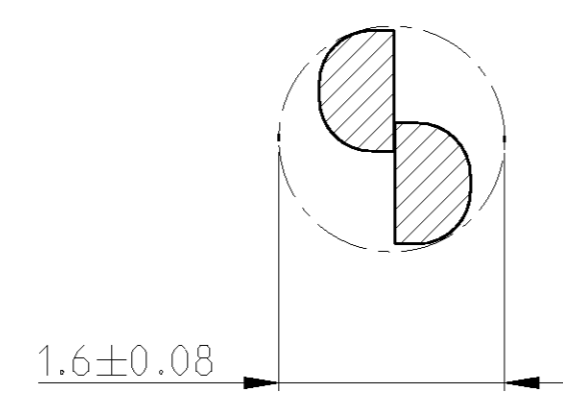
- NOTES:  
BEMERKUNGEN:
- ① 2 μm - 4 μm Sn OVER 1.2 μm - 2.7 μm Ni  
2 μm - 4 μm Sn UEBER 1.2 μm - 2.7 μm Ni
  - 2



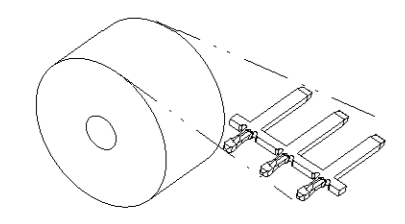
PLATED THROUGH HOLE SPECIFICATION SPEZIFIKATION FUER DURCHPLATIERTE BOHRUNGEN	
Cu THICKNESS KUPFER-SCHICHTDICKE	25-50 μm
Sn THICKNESS ZINN-SCHICHTDICKE	4-15 μm
DRILLED HOLE Ø1.5±0.025 BOHRLOCH-Ø1.5±0.025	FINISHED HOLE Ø1.29 <sup>+0.15</sup> PLATIIERTER LOCH-Ø1.29 <sup>+0.15</sup>

- ③ DIMENSION OF LOOSE PIESE  
MASS FUER EINZELTEIL
- ④ TO BE REELED ON PACAKE REEL WITH INTERLEAVING PAPER  
PAPPSPULEN MIT ZWISCHENLAGENPAPIER
- ⑤ TO BE REELED ON HARD FIBER REEL WITH INTERLEAVING PAPER  
HARTFASERSPULEN MIT ZWISCHENLAGENPAPIER
- ⑥ 0.7 μm - 2 μm Sn OVER 1.2 μm - 2.7 μm Ni (ACTION PIN AREA)  
0.7 μm - 2 μm Sn UEBER 1.2 μm - 2.7 μm Ni (ACTION PIN BEREICH)

A-A  
20:1



DIRECTION OFF  
TOP OF REEL



1-	-2
1-	-3
④	⑤

TYCO PART NO.	REV.	MATERIAL	SURFACE	REEL PACKING
1-1452692-3	A	Cu Sn 4	①	⑤
1-1452692-2	A	Cu Sn 4	①	④

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN P. Nickelfeld 20 JUL 2004	tyco Electronics AMP GmbH D - 64625 Bensheim
DIMENSIONS: mm		CHK J. Ryll 21 JUL 2004	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD -	NAME TAB 1.5 x 0.8 WITH ACTION PIN Flachstecker 1.5 x 0.8 mit ACTION PIN
0 PLC ±0.2 1 PLC ±0.1 2 PLC ± 3 PLC ± 4 PLC ±		PRODUCT SPEC 108-18867	SIZE A2
MATERIAL FINISH		APPLICATION SPEC 114-18570	CAGE CODE 00779
ANGLES FINISH		WEIGHT -	DRAWING NO 1452692
-		CUSTOMER DRAWING	RESTRICTED TO -
-		SCALE 10:1	SHEET 1 OF 1
-		REV A1	